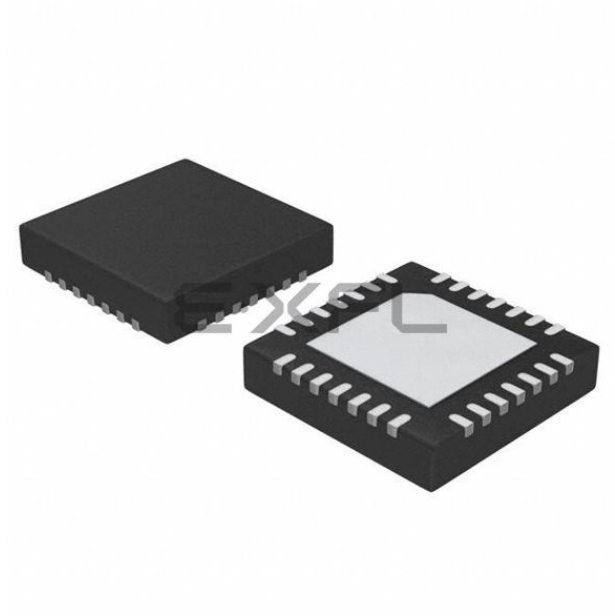
Microchip Technology - PIC24F08KL402T-I/MQ Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	24
Program Memory Size	8KB (2.75K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VFQFN Exposed Pad
Supplier Device Package	28-QFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24f08kl402t-i-mq

TABLE 1-4: PIC24F16KL40X/30X FAMILY PINOUT DESCRIPTIONS (CONTINUED)

Function	Pin Number				I/O	Buffer	Description
	20-Pin PDIP/ SSOP/ SOIC	20-Pin QFN	28-Pin SPDIP/ SSOP/ SOIC	28-Pin QFN			
PGEC1	5	2	5	2	I/O	ST	ICSP™ Clock 1
PCED1	4	1	4	1	I/O	ST	ICSP Data 1
PGEC2	2	19	22	19	I/O	ST	ICSP Clock 2
PGED2	3	20	21	18	I/O	ST	ICSP Data 2
PGEC3	10	7	15	12	I/O	ST	ICSP Clock 3
PGED3	9	6	14	11	I/O	ST	ICSP Data 3
RA0	2	19	2	27	I/O	ST	PORTA Pins
RA1	3	20	3	28	I/O	ST	
RA2	7	4	9	6	I/O	ST	
RA3	8	5	10	7	I/O	ST	
RA4	10	7	12	9	I/O	ST	
RA5	1	18	1	26	I	ST	
RA6	14	11	20	17	I/O	ST	
RA7	—	—	19	16	I/O	ST	
RB0	4	1	4	1	I/O	ST	PORTB Pins
RB1	5	2	5	2	I/O	ST	
RB2	6	3	6	3	I/O	ST	
RB3	—	—	7	4	I/O	ST	
RB4	9	6	11	8	I/O	ST	
RB5	—	—	14	11	I/O	ST	
RB6	—	—	15	12	I/O	ST	
RB7	11	8	16	13	I/O	ST	
RB8	12	9	17	14	I/O	ST	
RB9	13	10	18	15	I/O	ST	
RB10	—	—	21	18	I/O	ST	
RB11	—	—	22	19	I/O	ST	
RB12	15	12	23	20	I/O	ST	
RB13	16	13	24	21	I/O	ST	
RB14	17	14	25	22	I/O	ST	
RB15	18	15	26	23	I/O	ST	
REFO	18	15	26	23	O	—	Reference Clock Output
SCK1	15	12	22	19	I/O	ST	MSSP1 SPI Serial Input/Output Clock
SCK2	18	15	14	11	I/O	ST	MSSP2 SPI Serial Input/Output Clock
SCL1	12	9	17	14	I/O	I^2C	MSSP1 I^2C Clock Input/Output
SCL2	18	15	7	4	I/O	I^2C	MSSP2 I^2C Clock Input/Output
SCLKI	10	7	12	9	I	ST	Digital Secondary Clock Input
SDA1	13	10	18	15	I/O	I^2C	MSSP1 I^2C Data Input/Output
SDA2	2	19	2	27	I/O	I^2C	MSSP2 I^2C Data Input/Output
SDI1	17	14	21	18	I	ST	MSSP1 SPI Serial Data Input
SDI2	2	19	19	16	I	ST	MSSP2 SPI Serial Data Input
SDO1	16	13	24	21	O	—	MSSP1 SPI Serial Data Output
SDO2	3	20	15	12	O	—	MSSP2 SPI Serial Data Output

Legend: TTL = TTL input buffer
ANA = Analog level input/output
ST = Schmitt Trigger input buffer
I^2C = I^2C™/SMBus input buffer

TABLE 4-10: PORTA REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7(1)	Bit 6	Bit 5(2)	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISA	02C0	—	—	—	—	—	—	—	—	TRISA7	TRISA6	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	00DF
PORTA	02C2	—	—	—	—	—	—	—	—	RA7	RA6	RA5	RA4	RA3	RA2	RA1	RA0	xxxx
LATA	02C4	—	—	—	—	—	—	—	—	LATA7	LATA6	—	LATA4	LATA3	LATA2	LATA1	LATA0	xxxx
ODCA	02C6	—	—	—	—	—	—	—	—	ODA7	ODA6	—	ODA4	ODA3	ODA2	ODA1	ODA0	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: These ports and their associated bits are unimplemented on 14-pin and 20-pin devices; read as '0'.

2: PORTA<5> is unavailable when $\overline{\text{MCLR}}$ functionality is enabled (MCLRE Configuration bit = 1).

TABLE 4-11: PORTB REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13(1)	Bit 12(1)	Bit 11(2)	Bit 10(2)	Bit 9	Bit 8	Bit 7(1)	Bit 6(2)	Bit 5(2)	Bit 4	Bit 3(2)	Bit 2(1)	Bit 1(1)	Bit 0	All Resets
TRISB	02C8	TRISB15	TRISB14	TRISB13	TRISB12	TRISB11	TRISB10	TRISB9	TRISB8	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	FFFF
PORTB	02CA	RB15	RB14	RB13	RB12	RB11	RB10	RB9	RB8	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx
LATB	02CC	LATB15	LATB14	LATB13	LATB12	LATB11	LATB10	LATB9	LATB8	LATB7	LATB6	LATB5	LATB4	LATB3	LATB2	LATB1	LATB0	xxxx
ODCB	02CE	ODB15	ODB14	ODB13	ODB12	ODB11	ODB10	ODB9	ODB8	ODB7	ODB6	ODB5	ODB4	ODB3	ODB2	ODB1	ODB0	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: These ports and their associated bits are unimplemented on 14-pin and 20-pin devices.

2: These ports and their associated bits are unimplemented in 14-pin devices.

TABLE 4-12: PAD CONFIGURATION REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PADCFG1	02FC	—	—	—	—	SDO2DIS(1)	SCK2DIS(1)	SDO1DIS	SCK1DIS	—	—	—	—	—	—	—	—	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: These bits are unimplemented on PIC24FXXKL10X and PIC24FXXKL20X family devices; read as '0'.

REGISTER 6-1: NVMCON: NONVOLATILE MEMORY CONTROL REGISTER

R/SO-0, HC	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0
WR	WREN	WRERR	PGMONLY	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	ERASE	NVMOP5(1)	NVMOP4(1)	NVMOP3(1)	NVMOP2(1)	NVMOP1(1)	NVMOP0(1)
bit 7							bit 0

Legend:	HC = Hardware Clearable bit	U = Unimplemented bit, read as '0'	
R = Readable bit	W = Writable bit	SO = Settable Only bit	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **WR:** Write Control bit (program or erase)
1 = Initiates a data EEPROM erase or write cycle (can be set but not cleared in software)
0 = Write cycle is complete (cleared automatically by hardware)

bit 14 **WREN:** Write Enable bit (erase or program)
1 = Enables an erase or program operation
0 = No operation allowed (device clears this bit on completion of the write/erase operation)

bit 13 **WRERR:** Flash Error Flag bit
1 = A write operation is prematurely terminated (any $\overline{\text{MCLR}}$ or WDT Reset during programming operation)
0 = The write operation completed successfully

bit 12 **PGMONLY:** Program Only Enable bit
1 = Write operation is executed without erasing target address(es) first
0 = Automatic erase-before-write; write operations are preceded automatically by an erase of target address(es)

bit 11-7 **Unimplemented:** Read as '0'

bit 6 **ERASE:** Erase Operation Select bit
1 = Performs an erase operation when WR is set
0 = Performs a write operation when WR is set

bit 5-0 **NVMOP<5:0>:** Programming Operation Command Byte bits(1)
Erase Operations (when ERASE bit is '1'):
011010 = Erases 8 words
011001 = Erases 4 words
011000 = Erases 1 word
0100xx = Erases entire data EEPROM
Programming Operations (when ERASE bit is '0'):
001xxx = Writes 1 word

Note 1: These NVMOP configurations are unimplemented on PIC24F04KL10X and PIC24F08KL20X devices.

REGISTER 8-17: IPC0: INTERRUPT PRIORITY CONTROL REGISTER 0

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	T1IP2	T1IP1	T1IP0	—	CCP1IP2	CCP1IP1	CCP1IP0
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-0	R/W-0
—	—	—	—	—	INT0IP2	INT0IP1	INT0IP0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-12 **T1IP<2:0>:** Timer1 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as ‘0’

bit 10-8 **CCP1IP<2:0>:** Capture/Compare/PWM1 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 7-3 **Unimplemented:** Read as ‘0’

bit 2-0 **INT0IP<2:0>:** External Interrupt 0 Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

REGISTER 8-18: IPC1: INTERRUPT PRIORITY CONTROL REGISTER 1

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	T2IP2	T2IP1	T2IP0	—	CCP2IP2	CCP2IP1	CCP2IP0
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-12 **T2IP<2:0>:** Timer2 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as ‘0’

bit 10-8 **CCP2IP<2:0>:** Capture/Compare/PWM2 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 7-0 **Unimplemented:** Read as ‘0’

REGISTER 9-2: CLKDIV: CLOCK DIVIDER REGISTER

R/W-0	R/W-0	R/W-1	R/W-1	R/W-0	R/W-0	R/W-0	R/W-1
ROI	DOZE2	DOZE1	DOZE0	DOZEN(1)	RCDIV2	RCDIV1	RCDIV0
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ROI:** Recover on Interrupt bit
1 = Interrupts clear the DOZEN bit, and reset the CPU and peripheral clock ratio to 1:1
0 = Interrupts have no effect on the DOZEN bit

bit 14-12 **DOZE<2:0>:** CPU-to-Peripheral Clock Ratio Select bits
111 = 1:128
110 = 1:64
101 = 1:32
100 = 1:16
011 = 1:8
010 = 1:4
001 = 1:2
000 = 1:1

bit 11 **DOZEN:** DOZE Enable bit(1)
1 = DOZE<2:0> bits specify the CPU-to-peripheral clock ratio
0 = CPU and the peripheral clock ratio are set to 1:1

bit 10-8 **RCDIV<2:0>:** FRC Postscaler Select bits
When COSC<2:0> (OSCCON<14:12) = 111 or 001:
111 = 31.25 kHz (divide-by-256)
110 = 125 kHz (divide-by-64)
101 = 250 kHz (divide-by-32)
100 = 500 kHz (divide-by-16)
011 = 1 MHz (divide-by-8)
010 = 2 MHz (divide-by-4)
001 = 4 MHz (divide-by-2) (default)
000 = 8 MHz (divide-by-1)
When COSC<2:0> (OSCCON<14:12>) = 110:
111 = 1.95 kHz (divide-by-256)
110 = 7.81 kHz (divide-by-64)
101 = 15.62 kHz (divide-by-32)
100 = 31.25 kHz (divide-by-16)
011 = 62.5 kHz (divide-by-8)
010 = 125 kHz (divide-by-4)
001 = 250 kHz (divide-by-2) (default)
000 = 500 kHz (divide-by-1)

bit 7-0 **Unimplemented:** Read as '0'

Note 1: This bit is automatically cleared when the ROI bit is set and an interrupt occurs.

12.0 TIMER1

Note:	This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on Timers, refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"Timers"** (DS39704).

The Timer1 module is a 16-bit timer which can operate as a free-running, interval timer/counter, or serve as the time counter for a software-based Real-Time Clock (RTC). Timer1 is only reset on initial VDD power-on events. This allows the timer to continue operating as an RTC clock source through other types of device Reset.

Timer1 can operate in three modes:

- 16-Bit Timer
- 16-Bit Synchronous Counter
- 16-Bit Asynchronous Counter

Timer1 also supports these features:

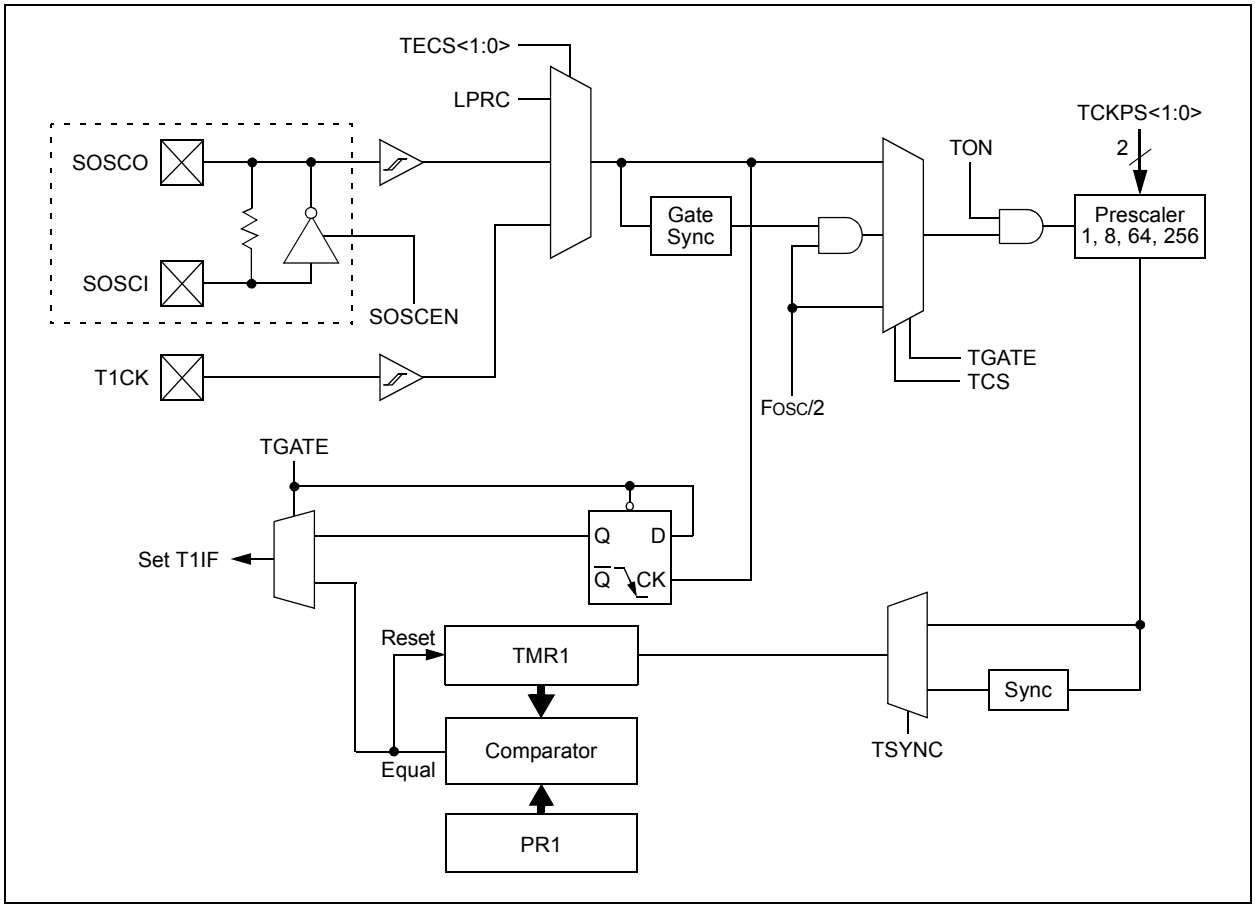
- Timer Gate Operation
- Selectable Prescaler Settings
- Timer Operation During CPU Idle and Sleep modes
- Interrupt on 16-Bit Period Register Match or Falling Edge of External Gate Signal

Figure 12-1 illustrates a block diagram of the 16-bit Timer1 module.

To configure Timer1 for operation:

1. Set the TON bit (= 1).
2. Select the timer prescaler ratio using the TCKPS<1:0> bits.
3. Set the Clock and Gating modes using the TCS and TGATE bits.
4. Set or clear the TSYNC bit to configure synchronous or asynchronous operation.
5. Load the timer period value into the PR1 register.
6. If interrupts are required, set the Timer1 Interrupt Enable bit, T1IE. Use the Timer1 Interrupt Priority bits, T1IP<2:0>, to set the interrupt priority.

FIGURE 12-1: 16-BIT TIMER1 MODULE BLOCK DIAGRAM



REGISTER 14-1: T3CON: TIMER3 CONTROL REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0
TMR3CS1	TMR3CS0	T3CKPS1	T3CKPS0	T3OSCEN	$\overline{\text{T3SYNC}}$	—	TMR3ON
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'

bit 7-6 **TMR3CS<1:0>:** Timer3 Clock Source Select bits
11 = Low-Power RC Oscillator (LPRC)
10 = External clock source (selected by T3CON<3>)
01 = Instruction clock (FOSC/2)
00 = System clock (FOSC)**(1)**

bit 5-4 **T3CKPS<1:0>**: Timer3 Input Clock Prescale Select bits
11 = 1:8 Prescale value
10 = 1:4 Prescale value
01 = 1:2 Prescale value
00 = 1:1 Prescale value

bit 3 **T3OSCEN**: Timer3 Oscillator Enable bit
1 = SOSC (Secondary Oscillator) is used as a clock source
0 = T3CK digital input pin is used as a clock source

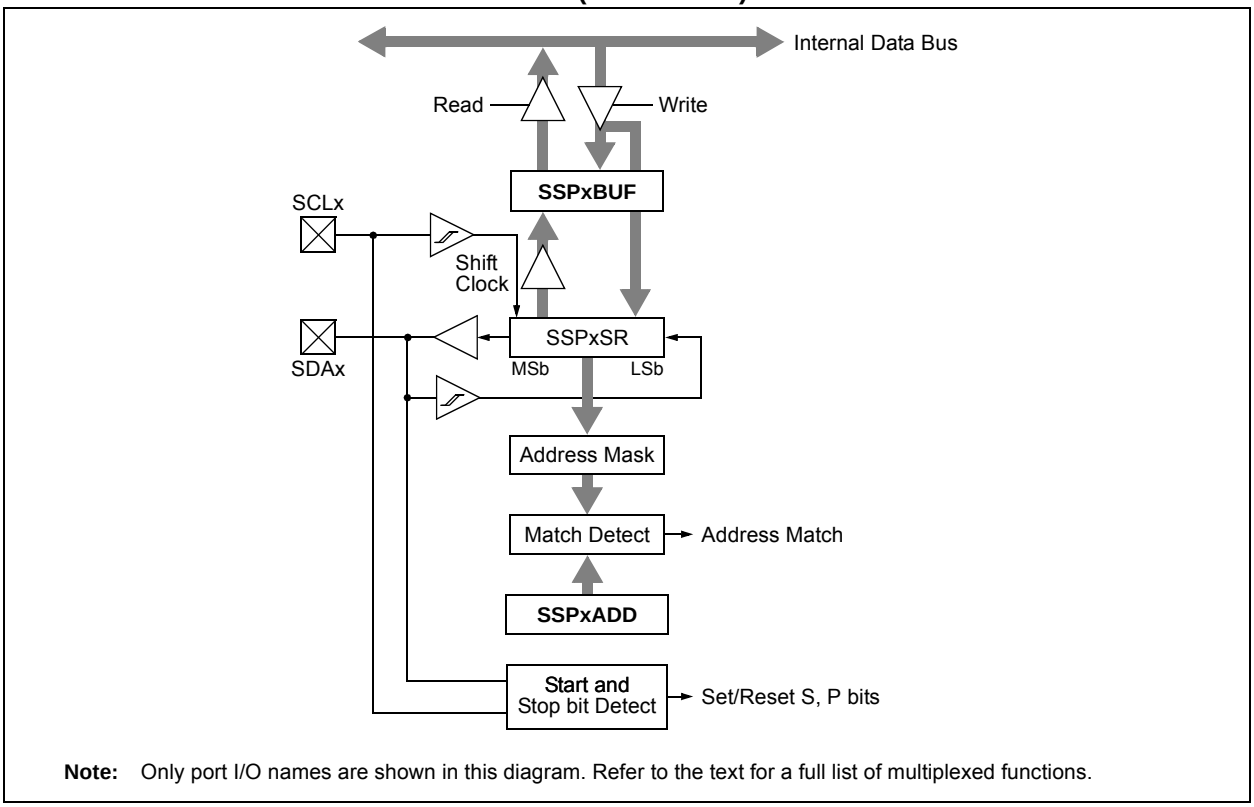
bit 2 **$\overline{\text{T3SYNC}}$:** Timer3 External Clock Input Synchronization Control bit
When TMR3CS<1:0> = 1x:
1 = Does not synchronize the external clock input
0 = Synchronizes the external clock input**(2)**
When TMR3CS<1:0> = 0x:
This bit is ignored; Timer3 uses the internal clock.

bit 1 **Unimplemented:** Read as '0'

bit 0 **TMR3ON:** Timer3 On bit
1 = Enables Timer3
0 = Stops Timer3

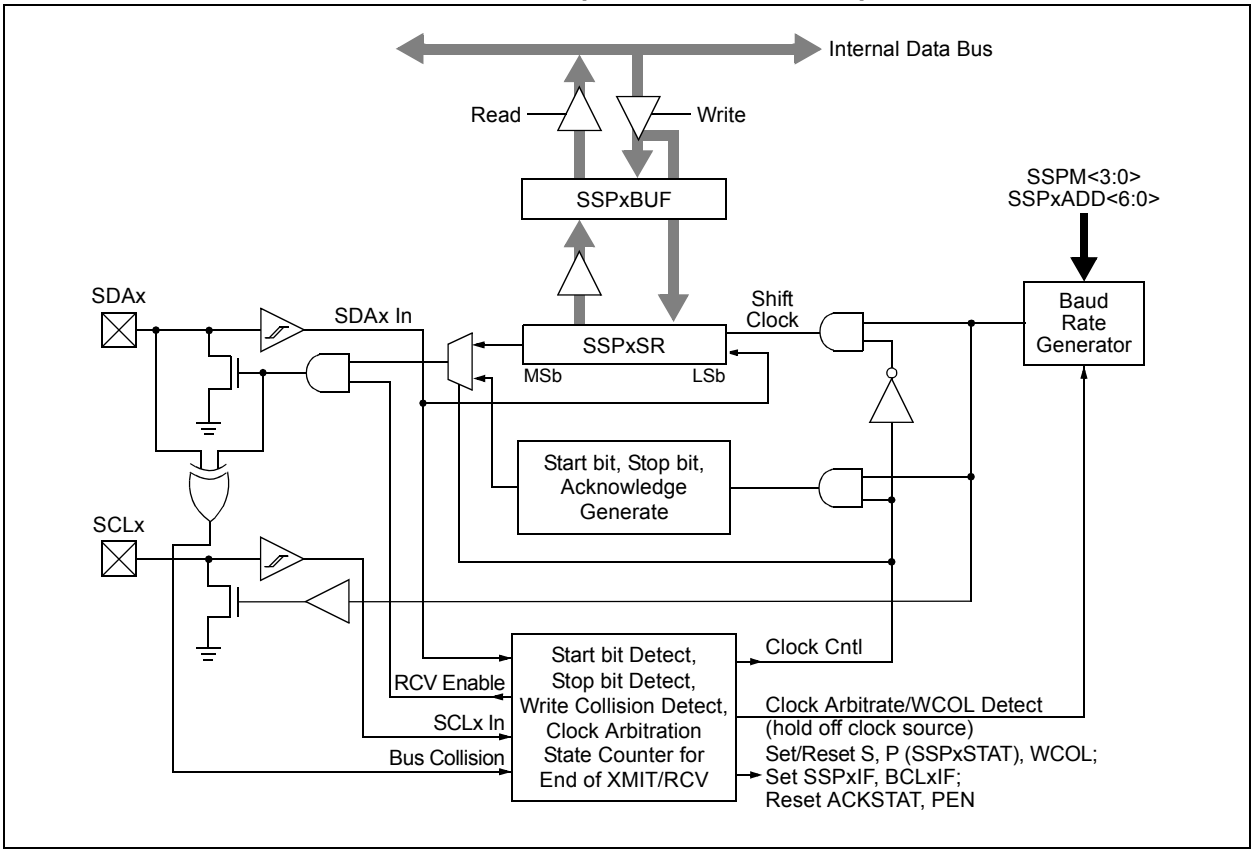
Note 1: The FOSC clock source should not be selected if the timer will be used with the ECCP capture or compare features.
2: This option must be selected when the timer will be used with ECCP/CCP.

FIGURE 17-3: MSSPx BLOCK DIAGRAM (I²C™ MODE)



Note: Only port I/O names are shown in this diagram. Refer to the text for a full list of multiplexed functions.

FIGURE 17-4: MSSPx BLOCK DIAGRAM (I²C™ MASTER MODE)



REGISTER 17-5: SSPxCON2: MSSPx CONTROL REGISTER 2 (I^2C™ MODE)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
GCEN	ACKSTAT	ACKDT(1)	ACKEN(2)	RCEN(2)	PEN(2)	RSEN(2)	SEN(2)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'

bit 7 **GCEN:** General Call Enable bit (Slave mode only)
1 = Enables interrupt when a general call address (0000h) is received in the SSPxSR
0 = General call address is disabled

bit 6 **ACKSTAT:** Acknowledge Status bit (Master Transmit mode only)
1 = Acknowledge was not received from slave
0 = Acknowledge was received from slave

bit 5 **ACKDT:** Acknowledge Data bit (Master Receive mode only)(1)
1 = No Acknowledge
0 = Acknowledge

bit 4 **ACKEN:** Acknowledge Sequence Enable bit (Master mode only)(2)
1 = Initiates Acknowledge sequence on SDAx and SCLx pins, and transmits ACKDT data bit; automatically cleared by hardware
0 = Acknowledge sequence is Idle

bit 3 **RCEN:** Receive Enable bit (Master Receive mode only)(2)
1 = Enables Receive mode for I^2C
0 = Receive is Idle

bit 2 **PEN:** Stop Condition Enable bit (Master mode only)(2)
1 = Initiates Stop condition on SDAx and SCLx pins; automatically cleared by hardware
0 = Stop condition is Idle

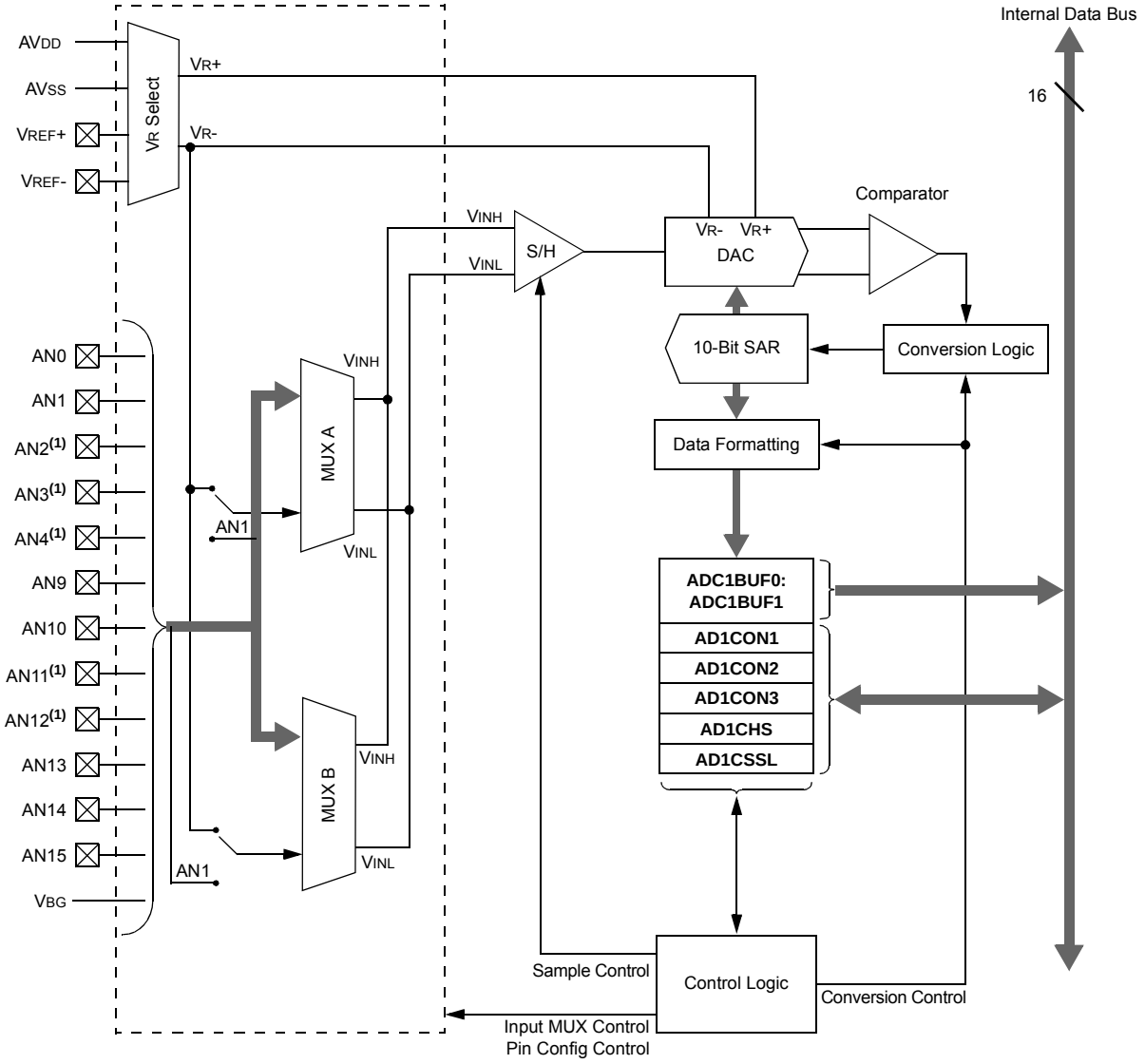
bit 1 **RSEN:** Repeated Start Condition Enable bit (Master mode only)(2)
1 = Initiates Repeated Start condition on SDAx and SCLx pins; automatically cleared by hardware
0 = Repeated Start condition is Idle

bit 0 **SEN:** Start Condition Enable bit(2)
Master Mode:
1 = Initiates Start condition on SDAx and SCLx pins; automatically cleared by hardware
0 = Start condition is Idle
Slave Mode:
1 = Clock stretching is enabled for both slave transmit and slave receive (stretch is enabled)
0 = Clock stretching is disabled

Note 1: The value that will be transmitted when the user initiates an Acknowledge sequence at the end of a receive.

2: If the I^2C module is active, these bits may not be set (no spooling) and the SSPxBUF may not be written (or writes to the SSPxBUF are disabled).

FIGURE 19-1: 10-BIT HIGH-SPEED A/D CONVERTER BLOCK DIAGRAM



Note 1: Unimplemented in 14-pin devices.

REGISTER 22-1: HLVDCON: HIGH/LOW-VOLTAGE DETECT CONTROL REGISTER

R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
HLVDEN	—	HLSIDL	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
VDIR	BGVST	IRVST	—	HLVDL3	HLVDL2	HLVDL1	HLVDL0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **HLVDEN:** High/Low-Voltage Detect Power Enable bit
1 = HLVD is enabled
0 = HLVD is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **HLSIDL:** HLVD Stop in Idle Mode bit
1 = Discontinues module operation when the device enters Idle mode
0 = Continues module operation in Idle mode

bit 12-8 **Unimplemented:** Read as '0'

bit 7 **VDIR:** Voltage Change Direction Select bit
1 = Event occurs when the voltage equals or exceeds the trip point (HLVDL<3:0>)
0 = Event occurs when the voltage equals or falls below the trip point (HLVDL<3:0>)

bit 6 **BGVST:** Band Gap Voltage Stable Flag bit
1 = Indicates that the band gap voltage is stable
0 = Indicates that the band gap voltage is unstable

bit 5 **IRVST:** Internal Reference Voltage Stable Flag bit
1 = Indicates that the internal reference voltage is stable and the High-Voltage Detect logic generates the interrupt flag at the specified voltage range
0 = Indicates that the internal reference voltage is unstable and the High-Voltage Detect logic will not generate the interrupt flag at the specified voltage range, and the HLVD interrupt should not be enabled

bit 4 **Unimplemented:** Read as '0'

bit 3-0 **HLVDL<3:0>:** High/Low-Voltage Detection Limit bits
1111 = External analog input is used (input comes from the HLVDIN pin)
1110 = Trip Point 14**(1)**
1101 = Trip Point 13**(1)**
1100 = Trip Point 12**(1)**
.
.
.
0000 = Trip Point 0**(1)**

Note 1: For the actual trip point, see **Section 26.0 "Electrical Characteristics"**.

25.0 INSTRUCTION SET SUMMARY

Note: This chapter is a brief summary of the PIC24F Instruction Set Architecture (ISA) and is not intended to be a comprehensive reference source.

The PIC24F instruction set adds many enhancements to the previous PIC® MCU instruction sets, while maintaining an easy migration from previous PIC MCU instruction sets. Most instructions are a single program memory word. Only three instructions require two program memory locations.

Each single-word instruction is a 24-bit word divided into an 8-bit opcode, which specifies the instruction type and one or more operands, which further specify the operation of the instruction. The instruction set is highly orthogonal and is grouped into four basic categories:

- Word or byte-oriented operations
- Bit-oriented operations
- Literal operations
- Control operations

Table 25-1 lists the general symbols used in describing the instructions. The PIC24F instruction set summary in Table 25-2 lists all the instructions, along with the status flags affected by each instruction.

Most word or byte-oriented W register instructions (including barrel shift instructions) have three operands:

- The first source operand, which is typically a register ‘Wb’ without any address modifier
- The second source operand, which is typically a register ‘Ws’ with or without an address modifier
- The destination of the result, which is typically a register ‘Wd’ with or without an address modifier

However, word or byte-oriented file register instructions have two operands:

- The file register specified by the value, ‘f’
- The destination, which could either be the file register, ‘f’, or the W0 register, which is denoted as ‘WREG’

Most bit-oriented instructions (including simple rotate/shift instructions) have two operands:

- The W register (with or without an address modifier) or file register (specified by the value of ‘Ws’ or ‘f’)
- The bit in the W register or file register (specified by a literal value or indirectly by the contents of register, ‘Wb’)

The literal instructions that involve data movement may use some of the following operands:

- A literal value to be loaded into a W register or file register (specified by the value of ‘k’)
- The W register or file register where the literal value is to be loaded (specified by ‘Wb’ or ‘f’)

However, literal instructions that involve arithmetic or logical operations use some of the following operands:

- The first source operand, which is a register ‘Wb’ without any address modifier
- The second source operand, which is a literal value
- The destination of the result (only if not the same as the first source operand), which is typically a register ‘Wd’ with or without an address modifier

The control instructions may use some of the following operands:

- A program memory address
- The mode of the Table Read and Table Write instructions

All instructions are a single word, except for certain double-word instructions, which were made double-word instructions so that all of the required information is available in these 48 bits. In the second word, the 8 MSbs are ‘0’s. If this second word is executed as an instruction (by itself), it will execute as a NOP.

Most single-word instructions are executed in a single instruction cycle, unless a conditional test is true or the Program Counter (PC) is changed as a result of the instruction. In these cases, the execution takes two instruction cycles, with the additional instruction cycle(s) executed as a NOP. Notable exceptions are the BRA (unconditional/computed branch), indirect CALL/GOTO, all Table Reads and Table Writes, and RETURN/RETFIE instructions, which are single-word instructions but take two or three cycles.

Certain instructions that involve skipping over the subsequent instruction require either two or three cycles if the skip is performed, depending on whether the instruction being skipped is a single-word or two-word instruction. Moreover, double-word moves require two cycles. The double-word instructions execute in two instruction cycles.

TABLE 26-6: DC CHARACTERISTICS: OPERATING CURRENT (I_{DD})(2)

DC CHARACTERISTICS			Standard Operating Conditions: 1.8V to 3.6V Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Parameter No.	**Typical(1)**	**Max**	**Units**	**Conditions**		
IDD Current						
DC20	0.154	0.350	mA	1.8V	+85V°C	0.5 MIPS, FOSC = 1 MHz
	0.301	0.630		3.3V		
	—	.500	mA	1.8V	+125°C	
	—	.800		3.3V		
DC22	0.300	—	mA	1.8V	+85°C	1 MIPS, FOSC = 2 MHz
	0.585	—		3.3V		
DC24	7.76	12.0	mA	3.3V	+85°C	16 MIPS, FOSC = 32 MHz
	—	18.0		3.3V	+125°C	
DC26	1.44	—	mA	1.8V	+85°C	FRC (4 MIPS), FOSC = 8 MHz
	2.71	—		3.3V		
DC30	4.00	28.0	µA	1.8V	+85°C	LPRC (15.5 KIPS), FOSC = 31 kHz
	9.00	55.0		3.3V		
	—	45.0	µA	1.8V	+125°C	
	—	90.0		3.3V		

Note 1: Data in the Typical column is at 3.3V, +25°C, unless otherwise stated.

2: IDD is measured with all peripherals disabled. All I/Os are configured as outputs and set low; PMDx bits are set to '1' and WDT, etc., are all disabled.

TABLE 26-7: DC CHARACTERISTICS: IDLE CURRENT (I_{IDLE})(2)

DC CHARACTERISTICS			Standard Operating Conditions: 1.8V to 3.6V Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Parameter No.	**Typical(1)**	**Max**	**Units**	**Conditions**		
Idle Current (IIDLE)						
DC40	0.035	0.080	mA	1.8V	+85°C	0.5 MIPS, FOSC = 1 MHz
	0.077	0.150		3.3V		
	—	0.160	mA	1.8V	+125°C	
	—	0.300		3.3V		
DC42	0.076	—	mA	1.8V	+85°C	1 MIPS, FOSC = 2 MHz
	0.146	—		3.3V		
DC44	2.52	3.20	mA	3.3V	+85°C	16 MIPS, FOSC = 32 MHz
	—	5.00	mA	3.3V	+125°C	
DC46	0.45	—	mA	1.8V	+85°C	FRC (4 MIPS), FOSC = 8 MHz
	0.76	—	mA	3.3V		
DC50	0.87	18.0	µA	1.8V	+85°C	LPRC (15.5 KIPS), FOSC = 31 kHz
	1.55	40.0	µA	3.3V		
	—	27.0	µA	1.8V	+125°C	
	—	50.0	µA	3.3V		

Note 1: Data in the Typical column is at 3.3V, +25°C, unless otherwise stated.

2: IIDLE is measured with all I/Os configured as outputs and set low; PMDx bits are set to '1' and WDT, etc., are all disabled.

TABLE 26-11: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 1.8V to 3.6V Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended					
Param No.	**Sym**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**	
	VOL	**Output Low Voltage**						
DO10		All I/O Pins	—	—	0.4	V	IOL = 4.0 mA	VDD = 3.6V
			—	—	0.4	V	IOL = 3.5 mA	VDD = 2.0V
DO16		OSC2/CLKO	—	—	0.4	V	IOL = 1.2 mA	VDD = 3.6V
			—	—	0.4	V	IOL = 0.4 mA	VDD = 2.0V
	VOH	**Output High Voltage**						
DO20		All I/O Pins	3	—	—	V	IOH = -3.0 mA	VDD = 3.6V
			1.6	—	—	V	IOH = -1.0 mA	VDD = 2.0V
DO26		OSC2/CLKO	3	—	—	V	IOH = -1.0 mA	VDD = 3.6V
			1.6	—	—	V	IOH = -0.5 mA	VDD = 2.0V

Note 1: Data in "Typ" column is at +25°C unless otherwise stated.

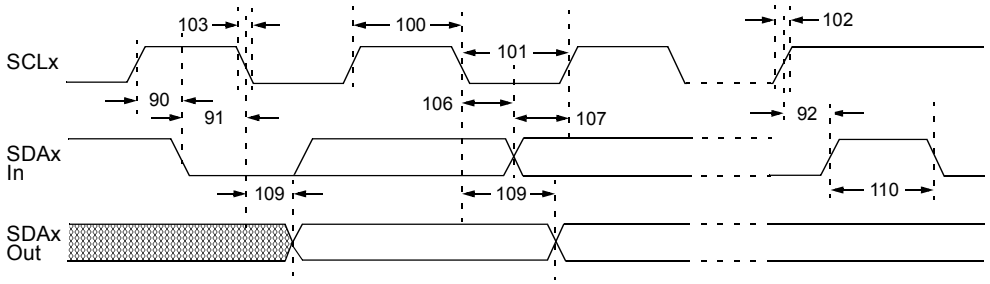
TABLE 26-12: DC CHARACTERISTICS: PROGRAM MEMORY

DC CHARACTERISTICS			Standard Operating Conditions: 1.8V to 3.6V Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
		Program Flash Memory					
D130	EP	Cell Endurance	10,000(2)	—	—	E/W	
D131	VPR	VDD for Read	VMIN	—	3.6	V	VMIN = Minimum operating voltage
D133A	TIW	Self-Timed Write Cycle Time	—	2	—	ms	
D134	TRETD	Characteristic Retention	40	—	—	Year	Provided no other specifications are violated
D135	IDDP	Supply Current During Programming	—	10	—	mA	

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

2: Self-write and block erase.

FIGURE 26-14: MSSPx I²C™ BUS DATA TIMING



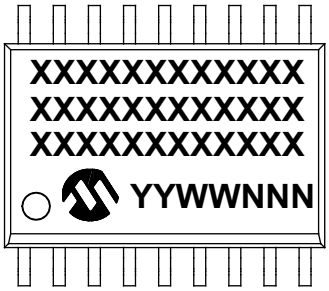
Note: Refer to Figure 26-3 for load conditions.

TABLE 26-34: I²C™ BUS DATA REQUIREMENTS (MASTER MODE)

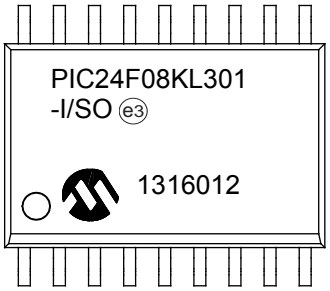
Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
100	THIGH	Clock High Time	100 kHz mode	2(TOSC)(BRG + 1)	—	—	
			400 kHz mode	2(TOSC)(BRG + 1)	—	—	
101	TLOW	Clock Low Time	100 kHz mode	2(TOSC)(BRG + 1)	—	—	
			400 kHz mode	2(TOSC)(BRG + 1)	—	—	
102	TR	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
103	TF	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
90	TSU:STA	Start Condition Setup Time	100 kHz mode	2(TOSC)(BRG + 1)	—	—	Only relevant for Repeated Start condition
			400 kHz mode	2(TOSC)(BRG + 1)	—	—	
91	THD:STA	Start Condition Hold Time	100 kHz mode	2(TOSC)(BRG + 1)	—	—	After this period, the first clock pulse is generated
			400 kHz mode	2(TOSC)(BRG + 1)	—	—	
106	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	μs	
107	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	**(Note 1)**
			400 kHz mode	100	—	ns	
92	TSU:STO	Stop Condition Setup Time	100 kHz mode	2(TOSC)(BRG + 1)	—	—	
			400 kHz mode	2(TOSC)(BRG + 1)	—	—	
109	TAA	Output Valid from Clock	100 kHz mode	—	3500	ns	
			400 kHz mode	—	1000	ns	
110	TBUF	Bus Free Time	100 kHz mode	4.7	—	μs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	μs	
D102	CB	Bus Capacitive Loading		—	400	pF	

Note 1: A Fast mode I²C bus device can be used in a Standard mode I²C bus system, but Parameter 107 ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCLx signal. If such a device does stretch the LOW period of the SCLx signal, it must output the next data bit to the SDAx line, Parameter 102 + Parameter 107 = 1000 + 250 = 1250 ns (for 100 kHz mode), before the SCLx line is released.

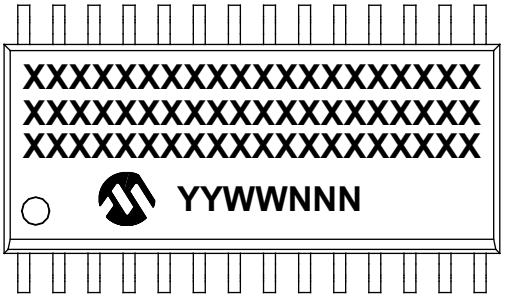
20-Lead SOIC (7.50 mm)



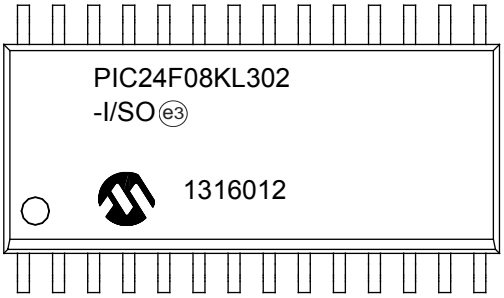
Example



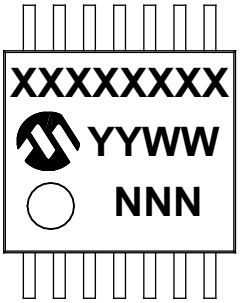
28-Lead SOIC (7.50 mm)



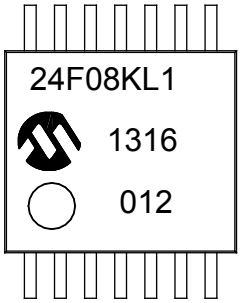
Example



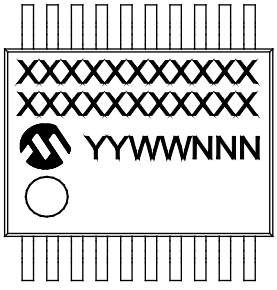
14-Lead TSSOP (4.4 mm)



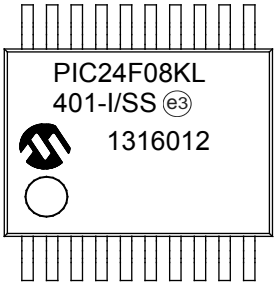
Example



20-Lead SSOP (5.30 mm)

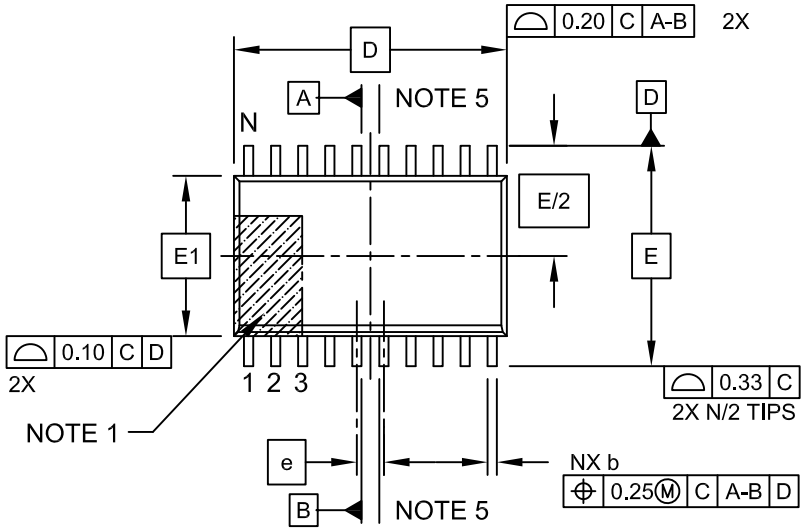


Example

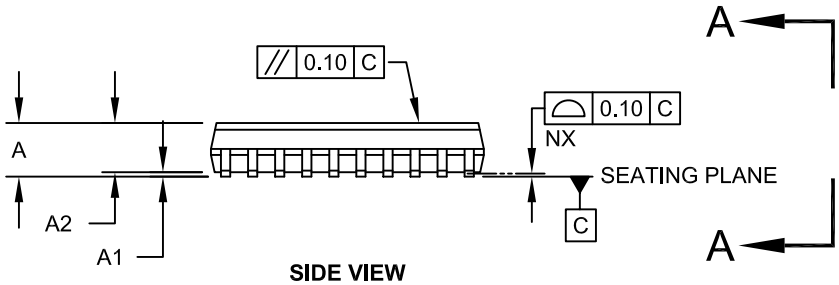


20-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

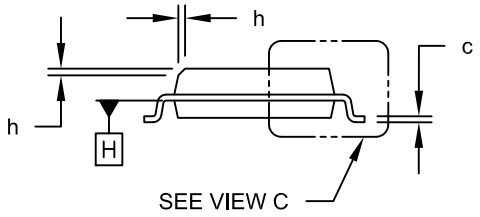
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW

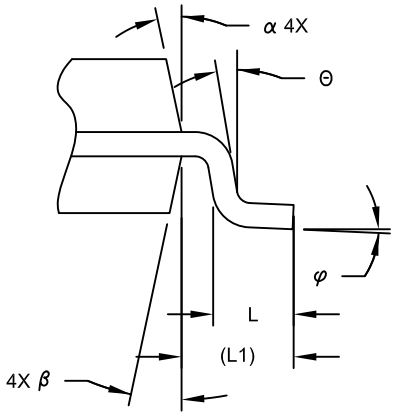


VIEW A-A

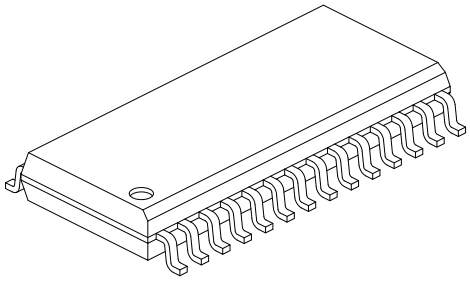
Microchip Technology Drawing C04-094C Sheet 1 of 2

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1		7.50 BSC	
Overall Length	D		17.90 BSC	
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1		1.40 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.18	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

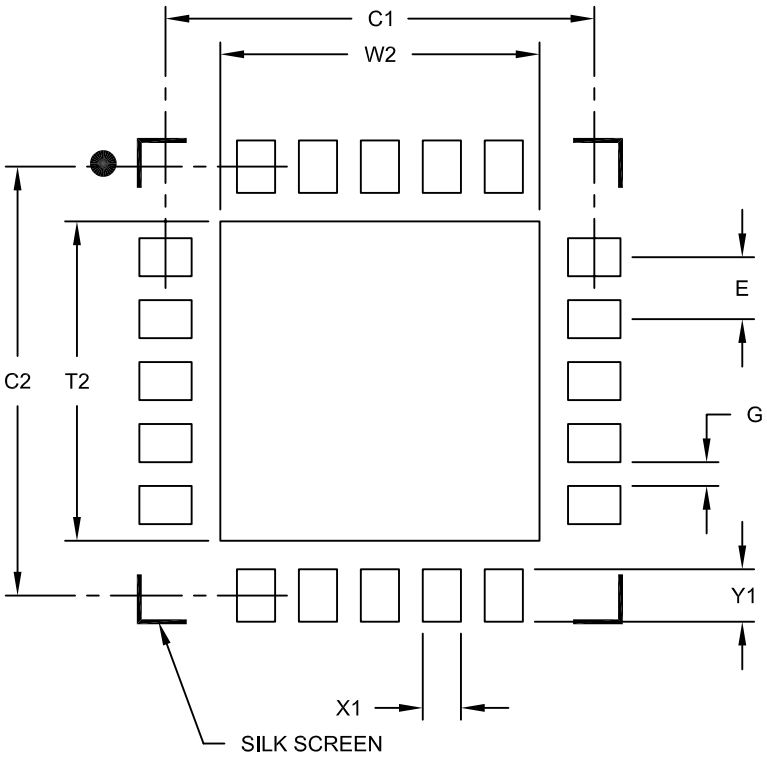
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing C04-052C Sheet 2 of 2

20-Lead Plastic Quad Flat, No Lead Package (MQ) - 5x5 mm Body [QFN]
With 0.40mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Optional Center Pad Width	W2			3.35
Optional Center Pad Length	T2			3.35
Contact Pad Spacing	C1		4.50	
Contact Pad Spacing	C2		4.50	
Contact Pad Width (X20)	X1			0.40
Contact Pad Length (X20)	Y1			0.55
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2139A